



Summary

The invention relates to a method for the manufacture of a leadless substrate with a basic body made of copper or copper base alloy, a solder layer applied onto at least one portion of the basic body and made of metals belonging the group of gold, gold alloy, silver, silver alloy, palladium, and palladium alloy, as well as an intermediate layer arranged between the basic body and the solder layer and made of nickel or nickel alloy. A cost-effective method for the manufacture of a leadless substrate is provided, with which a wetting time of less than one second is achieved after ageing according to DIN EN 60068-2-2, by forming the solder layer of at least two separate layers of different metals and depositing the intermediate layer and the separate layers by electroplating.

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